

### NCE N-Channel Enhancement Mode Power MOSFET

### **General Description**

The NCE7560K uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

#### **Features**

- $V_{DS}$ =75V;  $I_D$ =60A@  $V_{GS}$ =10V;  $R_{DS(ON)}$ <8.5mΩ @  $V_{GS}$ =10V
- Special process technology for high ESD capability
- Special designed for Convertors and power controls
- High density cell design for ultra low Rdson
- Fully characterized Avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation

## **Application**

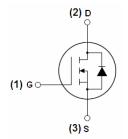
- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

#### **Product Summary**

BV <sub>DSS</sub> typ.	84	V
R <sub>DS(ON)</sub> typ.	6.8	mΩ
max.	8.5	mΩ
I <sub>D</sub>	60	Α

#### 100% UIS TESTED!





TO-252-2L top view

Schematic diagram

### Package Marking and Ordering Information

	J	<u> </u>			
Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE7560K	NCE7560K	TO-252-2L	-	-	-

### Table 1. Absolute Maximum Ratings (T<sub>C</sub>=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> =0V)	V <sub>DS</sub>	75	V
Gate-Source Voltage (V <sub>DS</sub> =0V)	$V_{GS}$	±20	V
Drain Current (DC) at Tc=25℃	I <sub>D (DC)</sub>	60	Α
Drain Current (DC) at Tc=100°C	I <sub>D (DC)</sub>	42	Α
Drain Current-Continuous@ Current-Pulsed (Note 1)	I <sub>DM (pluse)</sub>	310	А
Peak diode recovery voltage	dv/dt	30	V/ns
Maximum Power Dissipation(Tc=25℃)	P <sub>D</sub>	140	W
Derating factor		0.95	W/℃
Single pulse avalanche energy (Note 2)	E <sub>AS</sub>	300	mJ
Operating Junction and Storage Temperature Range	$T_{J}$ , $T_{STG}$	-55 To 175	$^{\circ}$ C

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2.EAS condition: Tj=25°C,VDD=37.5V,VG=10V,L=0.5mH



# **Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	1.05	°C/W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	50	°C/W

# Table 3. Electrical Characteristics (T<sub>C</sub>=25 ℃ unless otherwise noted)

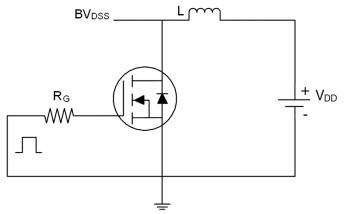
Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	75	84	-	V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =75V,V <sub>GS</sub> =0V	-	-	1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =75V,V <sub>GS</sub> =0V	-	-	10	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	2	3	4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	-	6.8	8.5	mΩ
Dynamic Characteristics						
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =30A		66	-	S
Input Capacitance	C <sub>lss</sub>	)/ OF)/)/ O)/		4400	-	PF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =25V,V <sub>GS</sub> =0V,		340	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz		260	-	PF
Total Gate Charge	Qg	V 20V/1 20A		100	-	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =30V,I <sub>D</sub> =30A,		20	-	nC
Gate-Drain Charge	$Q_{gd}$	- V <sub>GS</sub> =10V		30	-	nC
Switching times			•	•		
Turn-on Delay Time	t <sub>d(on)</sub>		-	17.8	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =30V, $I_{D}$ =2A, $R_{L}$ =15 $\Omega$	-	11.8	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10V, $R_{G}$ =2.5 $\Omega$	-	56	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	14.6	-	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>		-	-	80	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>		-	-	320	Α
Forward on voltage <sup>(Note 1)</sup>	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =30A,V <sub>GS</sub> =0V	-	-	1.2	V
Reverse Recovery Time <sup>(Note 1)</sup>	t <sub>rr</sub>	T:-05°0 L -75A d:/dt-400A/:	-	-	36	nS
Reverse Recovery Charge <sup>(Note 1)</sup>	Q <sub>rr</sub>	- Tj=25℃,I <sub>F</sub> =75A,di/dt=100A/μs	-	-	56	nC
Forward Turn-on Time	t <sub>on</sub>	Intrinsic turn-on time is negligible(turn-on is dominated by L <sub>S</sub> +L <sub>D</sub> )				y L <sub>S</sub> +L <sub>D</sub> )

### Notes

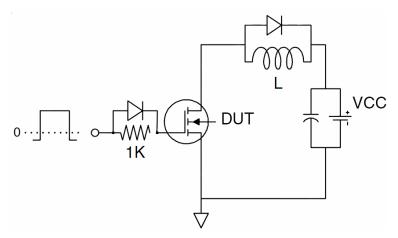
**<sup>1</sup>**.Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  1.5%, R<sub>G</sub>=25 $\Omega$ , Starting Tj=25 $^{\circ}$ C

# **Test Circuit**

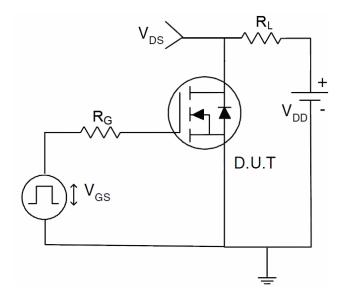
# 1) E<sub>AS</sub> test circuit



### 2) Gate charge test circuit



# 3) Switch Time Test Circuit





### **Typical Electrical and Thermal Characteristics (curves)**

Figure1. Safe operating area

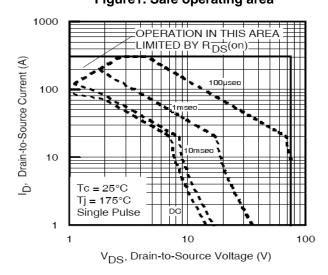


Figure3. Output characteristics

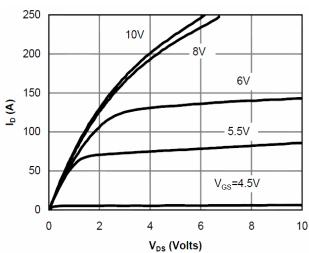


Figure 5. Static drain-source on resistance

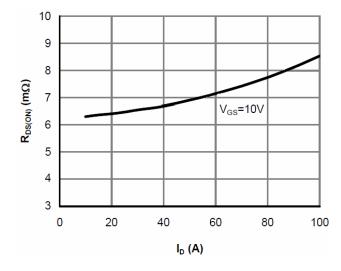


Figure 2. Source-Drain Diode Forward Voltage

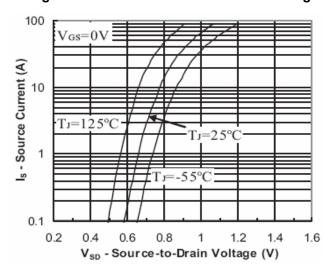


Figure 4. Transfer characteristics

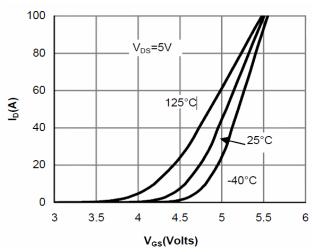
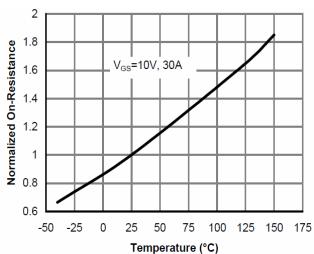


Figure 6. R<sub>DS(ON)</sub> vs Junction Temperature





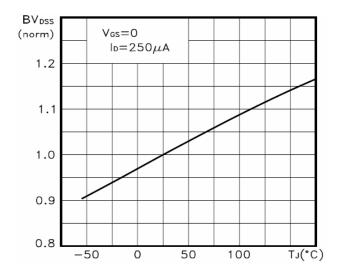


Figure 9. Gate charge waveforms

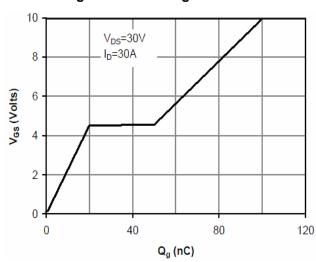


Figure 8. V<sub>GS(th)</sub> vs Junction Temperature

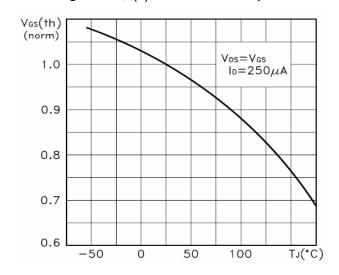


Figure 10. Capacitance

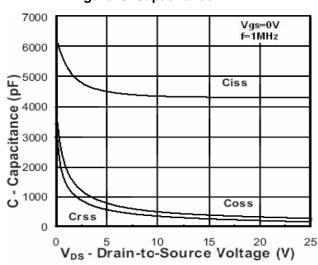
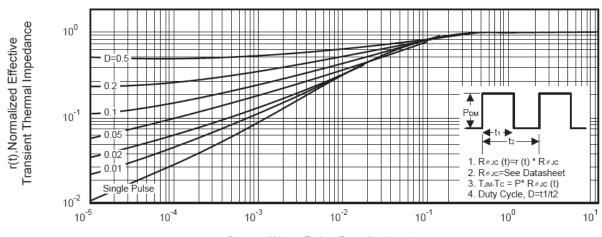
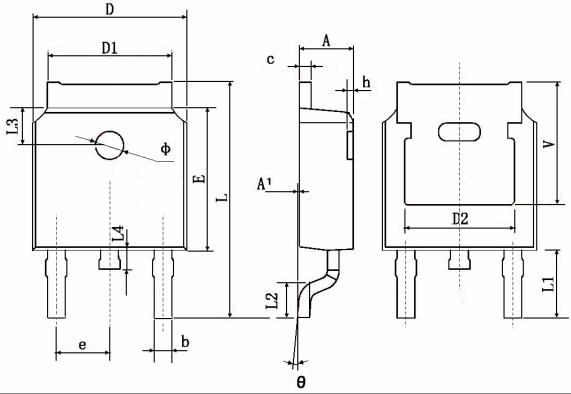


Figure 11. Normalized Maximum Transient Thermal Impedance



Square Wave Pulse Duration (sec)

# **TO-252 Package Information**



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		YP. 0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		

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